

Wiwynn OCP Design Contribution Guideline

Jan. 11, 2018

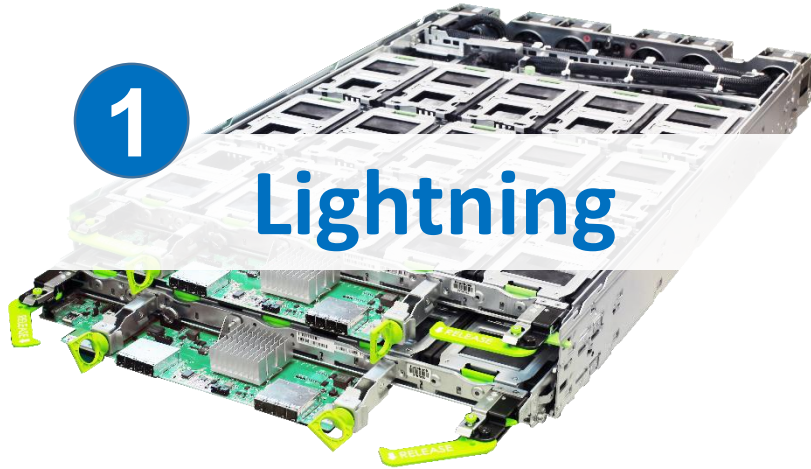


Agenda

- **2 Designs and 5 Product Contributions**
- **Datasheets**
- **System Block Diagrams**
- **Guide for Design Files**
(Bryce Canyon as the example)



2 Design and 5 Product Contribution List



1

Lightning

A

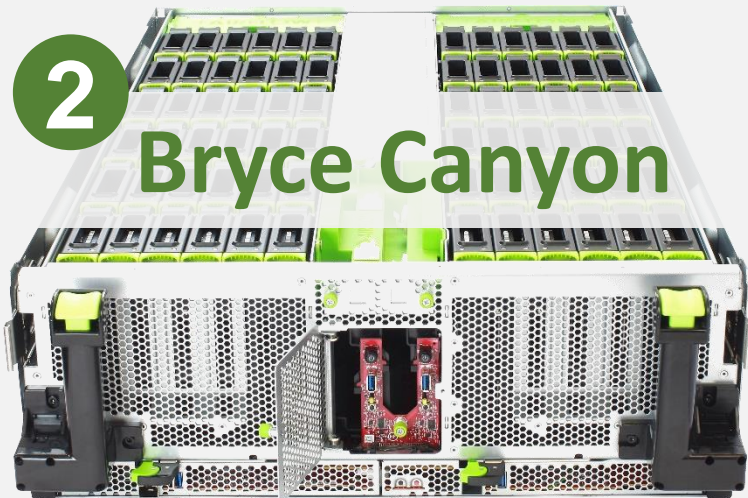
ST7200-30P

30 U.2 Bays

B

ST7200-60M

60 M.2 Bays



2

Bryce Canyon

A

SV7000G2

Mono
Lake

Mono
Lake

B

SV7000G2-L

Mono
Lake

IOM

C

ST7000G2

IOM

IOM



SV7200-30P/60M (Lightning Series) Datasheet

Model : Wiwynn ST7200-30P/60M

Storage and I/O

Expander	PCIe 3.0 Switch
Storage	60 M.2 NVMe SSDs: <ul style="list-style-type: none">• 22110 or 2280 30 U.2 NVMe SSDs <ul style="list-style-type: none">• 15mm or 7mm
Expansion Ports	Up to 4 PCIe 3.0 (x16) ports
Remote Management	BMC

Power Supply and Physical Specifications

Power Supply	Centralized 12V DC bus bar
Form Factor and Dimension	2 OU (Open Rack); 93.5(H) x 536 (W) x 795 (D)
Weight	38 kg ~ 55 kg



ST7000G2/SV7000G2 (Bryce Canyon) Datasheet

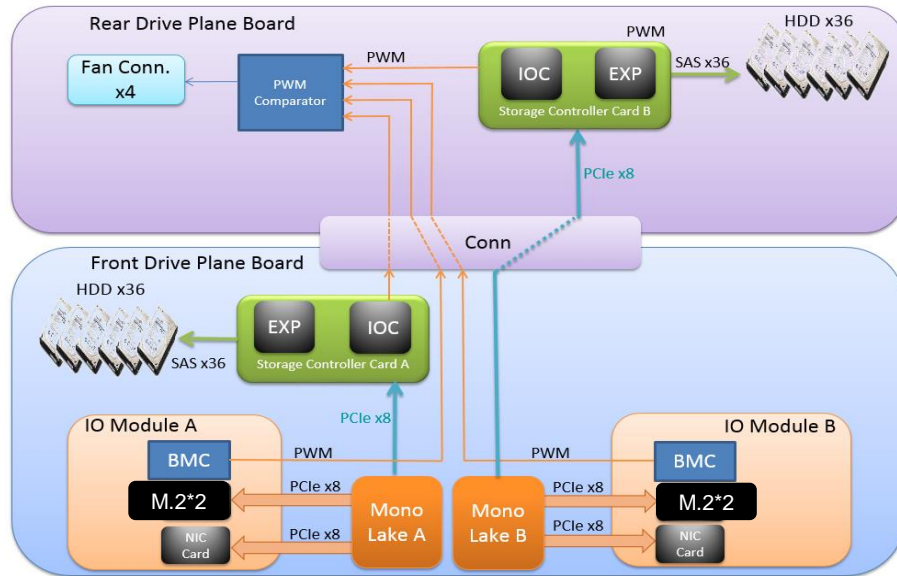
Model : Wiwynn ST7000G2/SV7200G2 Series

Storage and I/O	SV7000G2	SV7000G2-L	ST7000G2
Expander	SAS12G expander		
Storage	72 3.5" hot-plug drive bay		
Micro Server	2	1	
Processor	Intel® Xeon® Broadwell-DE	Intel® Xeon® Broadwell-DE	
Memory	DDR4 x 8 (4 per server), up to 2400MT/s	DDR4 x 4, up to 2400MT/s	
Boot Drive	2 x M.2 (1 per server)	1 x M.2	
IO Module (IOM)	2	1	
OCP Mezzanine	2 (1 per server)	1	
Expansion Ports	N/A	Two EXT mini-SAS 12G HD ports (SASx4)	Two EXT mini-SAS 12G HD ports (SASx4)
Remote Management	IPMI v2.0 Compliant, iKVM, Wiwynn Cluster Manager		SES, SMP
Power Supply and Physical Specifications			
Power Supply	Centralized 12.5 V DC bus bar		
Form Factor and Dimensions	4 OU Rack; 4U; 185 (H) x 537 (W) x 879 (D)		

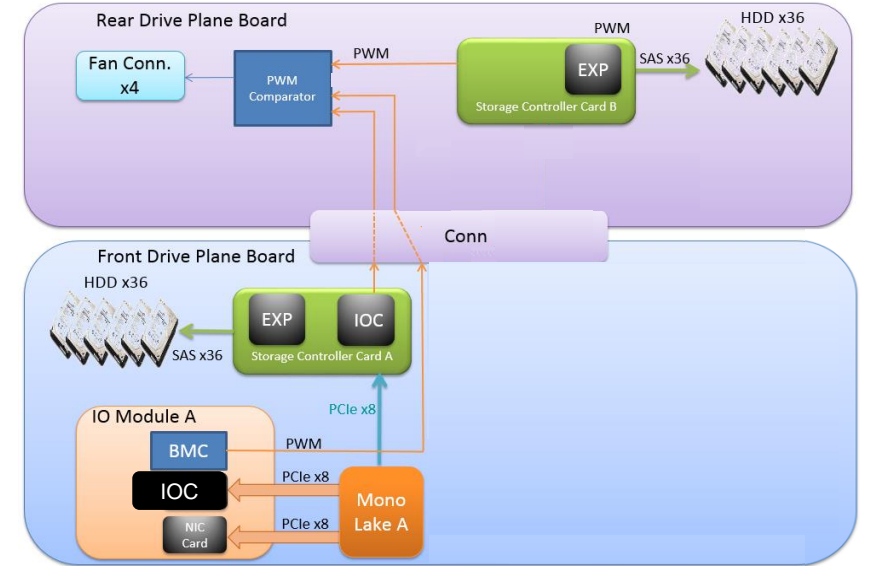
Bryce Canyon Contribution



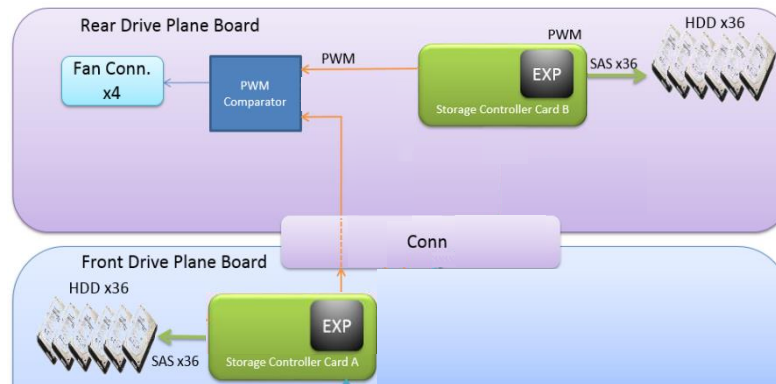
System Topology



SV7000G2



SV7000G2-L



ST7000G2



Design Files

The following folders are included in the zip file

➤ Schematic:

Contain designed DSN files (Cadence OrCAD) and .pdf files

➤ Layout and Stackup:

Contain designed BRD files (Allegro) and Excel files show detail stack up information

➤ BOMs (Bill of material):

An excel file shows full component information. (Including EE & ME)

➤ Manufacture files:

- Gerber files for PCB manufacture.
- Contain PCBAs DXF, PDF and EMN.

➤ MB Placement

➤ ME CAD(3D & 2D):

- Contain all system Solidworks files and neutral file. (STEP)
- Contain all chassis assemblies, metals, plastics, accessories, cables 2D files.

➤ oBMC:

- <https://github.com/facebook/openbmc>



Schematic

1. Schematic

- FDPB
- Front IO panel
- IOM_IOC
- IOM_M2
- LED board
- RDPB
- SCC



FDPB

- Front IO panel
- IOM_IOC
- IOM_M2
- LED board
- RDPB
- SCC



BRYCECANYON_FRONT_DPB_OCP_2011207.DSN
BRYCECANYON_FRONT_DPB_OCP_2011207.pdf



Bryce Canyon Front Drive Plan Board 36 HDDs

PCB P/N: 16315
Version: 1
Layer: 12 Layers

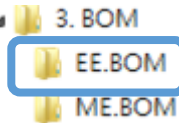
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06	POWER SEQUENCE	46	PCB 24		
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30	HDD 8	70	PCB 48		
31	HDD 9	71	PCB 49		
32	HDD 10	72	PCB 50		
33	HDD 11	73	PCB 51		
34	HDD 12	74	PCB 52		
35	HDD 13	75	PCB 53		
36	HDD 14	76	PCB 54		
37	HDD 15	77	PCB 55		
38	HDD 16	78	PCB 56		
39	HDD 17	79	PCB 57		
40	HDD 18	80	PCB 58		



The screenshot shows a Microsoft Excel spreadsheet titled "Print Drive Phase Board". The spreadsheet is organized into columns labeled A through Y. The data is presented in a table format with the following columns: Layer, Co Ut, Thickness, Glass/Copper Style, G1, and DSG1. The table lists various layers and their properties, including material, thickness, and style. The bottom of the spreadsheet includes a "Notes" section with three items: 1. Use a net, 2. The total thickness includes trace and solder mask, and 3. Minimum hole copper thickness is 0.01 mil. The spreadsheet is displayed in a window titled "Print Drive Phase Board - Setup.xlsx".

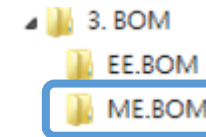
Layer	Co Ut	Thickness	Glass/Copper Style	G1	DSG1
Mask	0.0	0.0		3.4	0.025
Signal	0.0	0.0		3.4	0.025
Prepreg	0.0	0.0		3.4	0.025
Copper	0.0	0.0		3.4	0.025
Signal	0.0	0.0		3.4	0.025
Prepreg	0.0	0.0		3.4	0.025
Copper	0.0	0.0		3.4	0.025
Signal	0.0	0.0		3.4	0.025
Prepreg	0.0	0.0		3.4	0.025
Copper	0.0	0.0		3.4	0.025
Signal	0.0	0.0		3.4	0.025
Prepreg	0.0	0.0		3.4	0.025
Copper	0.0	0.0		3.4	0.025
Signal	0.0	0.0		3.4	0.025
Prepreg	0.0	0.0		3.4	0.025
Copper	0.0	0.0		3.4	0.025
Signal	0.0	0.0		3.4	0.025
Prepreg	0.0	0.0		3.4	0.025
Copper	0.0	0.0		3.4	0.025
Signal	0.0	0.0		3.4	0.025
Prepreg	0.0	0.0		3.4	0.025
Copper	0.0	0.0		3.4	0.025
Signal	0.0	0.0		3.4	0.025
Prepreg	0.0	0.0		3.4	0.025
Copper	0.0	0.0		3.4	0.025
Signal	0.0	0.0		3.4	0.025
Prepreg	0.0	0.0		3.4	0.025
Copper	0.0	0.0		3.4	0.025
Signal	0.0	0.0		3.4	0.025
Prepreg	0.0	0.0		3.4	0.025
Copper	0.0	0.0		3.4	0.025
Signal	0.0	0.0		3.4	0.025
Prepreg	0.0	0.0		3.4	0.025
Copper	0.0	0.0		3.4	0.025
Signal	0.0	0.0		3.4	0.025
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Signal	0.0	0.0		3.4	0.025
Prepreg	0.0	0.0		3.4	0.025
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Copper	0.0	0.0		3.4	0.025
Signal	0.0	0.0		3.4	0.025
Prepreg	0.0	0.0		3.4	0.025
Copper	0.0	0.0		3.4	0.025
Signal	0.0	0.0		3.4	0.025



5
★

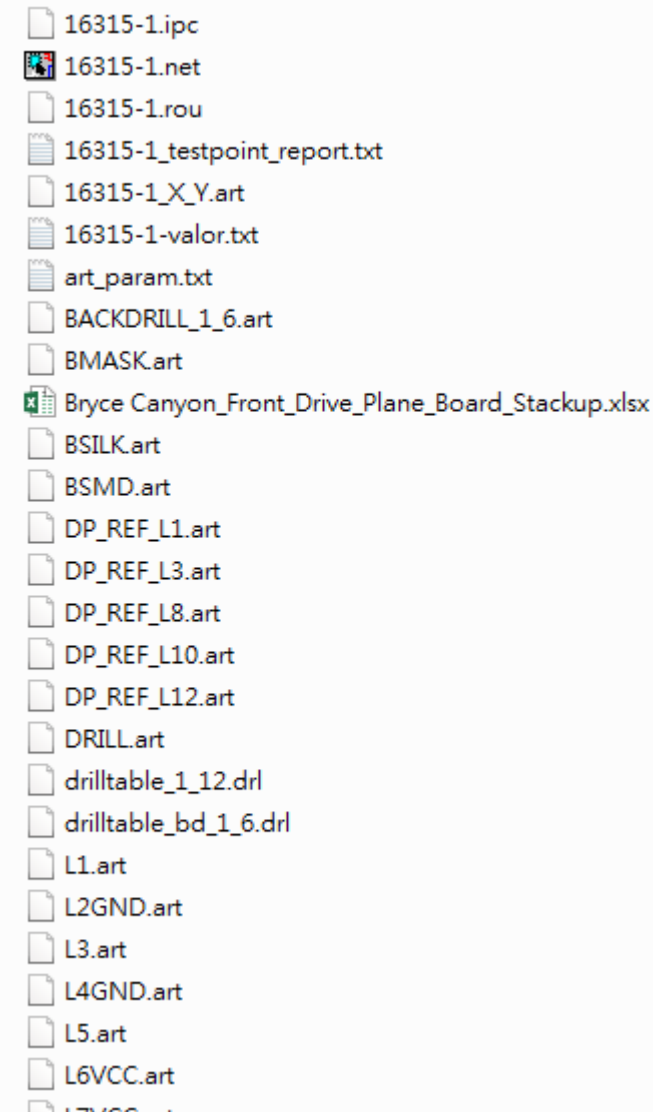
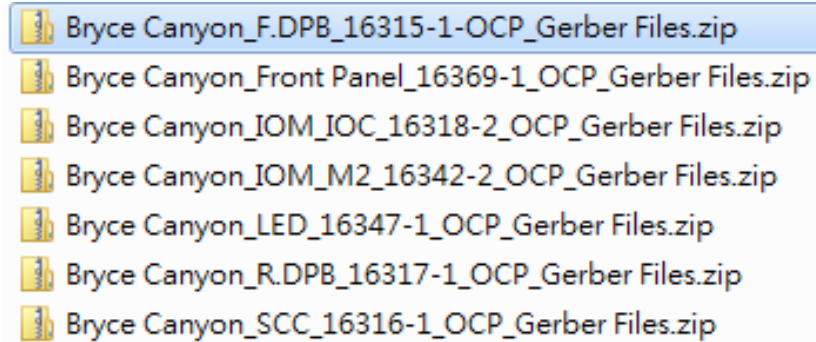
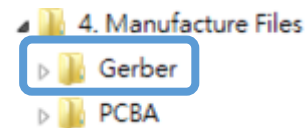
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7
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Manufacture Files _ Gerber





Manufacture Files _ PCBA

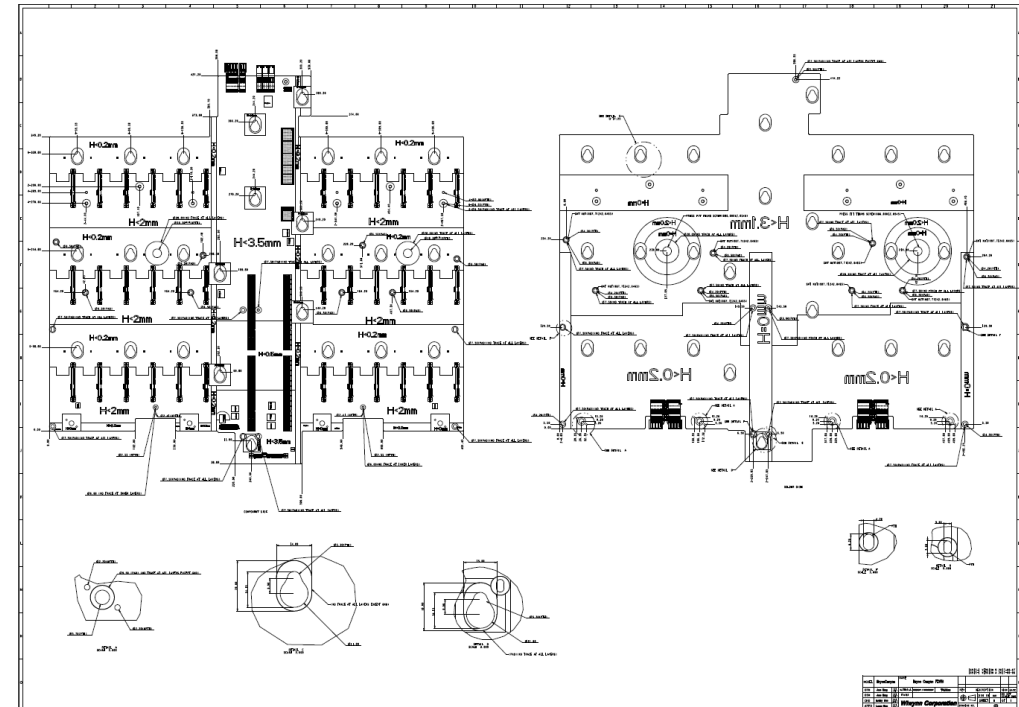
4. Manufacture Files

Gerber

PCBA

- 16315-1 FRONT DPB
- 16316-1 SCC
- 16317-1 REAR DPB
- 16318-2 IOM IOC
- 16342-2 IOM M.2
- 16347-SC LED BOARD
- 16369-SC FRONT IO BOARD

- 16315-1_0607_b
- 16315-1_0607_b.emn
- 16315-1_0607_B



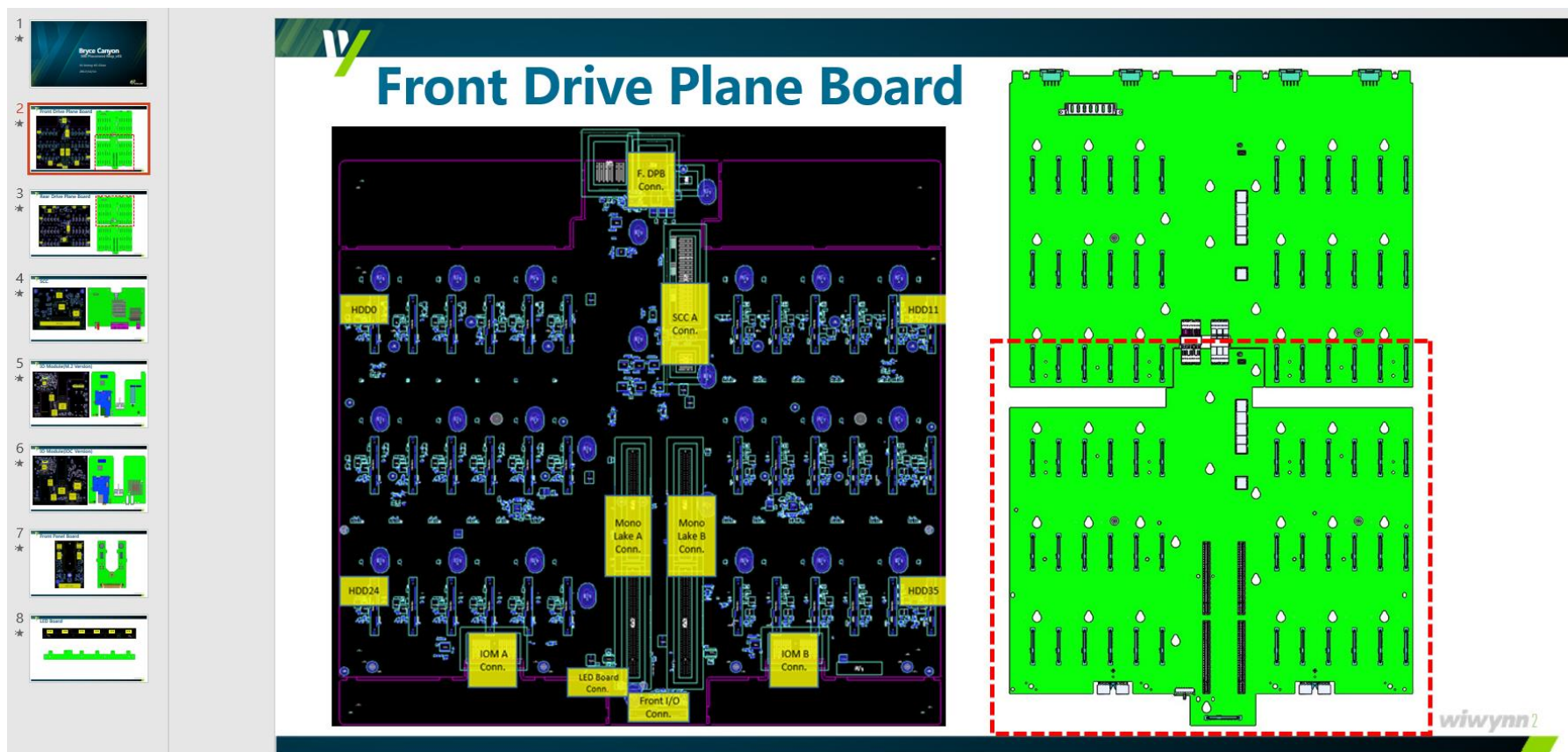


MB Placement

5. MB Placement

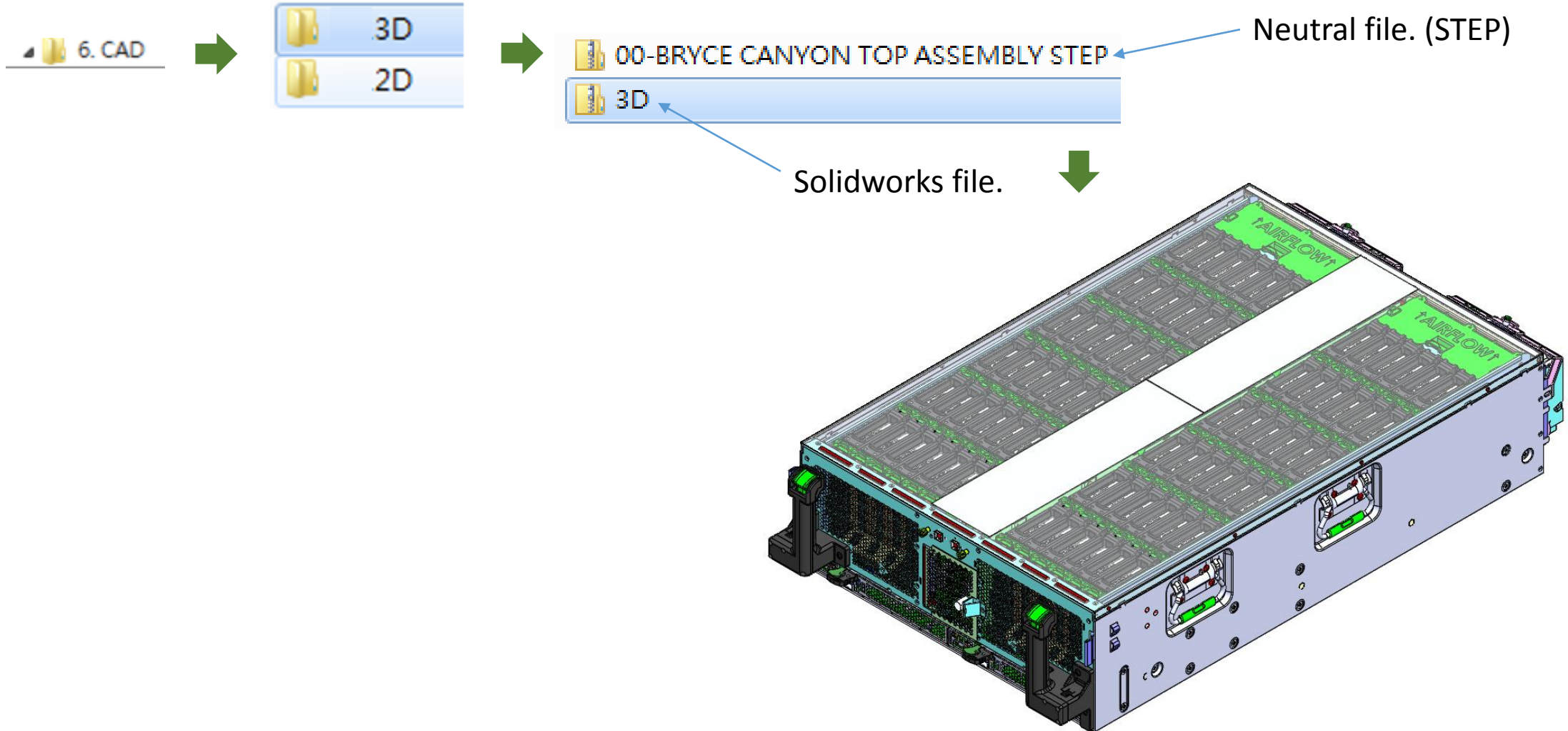


MB Placement Map_20171213.pptx



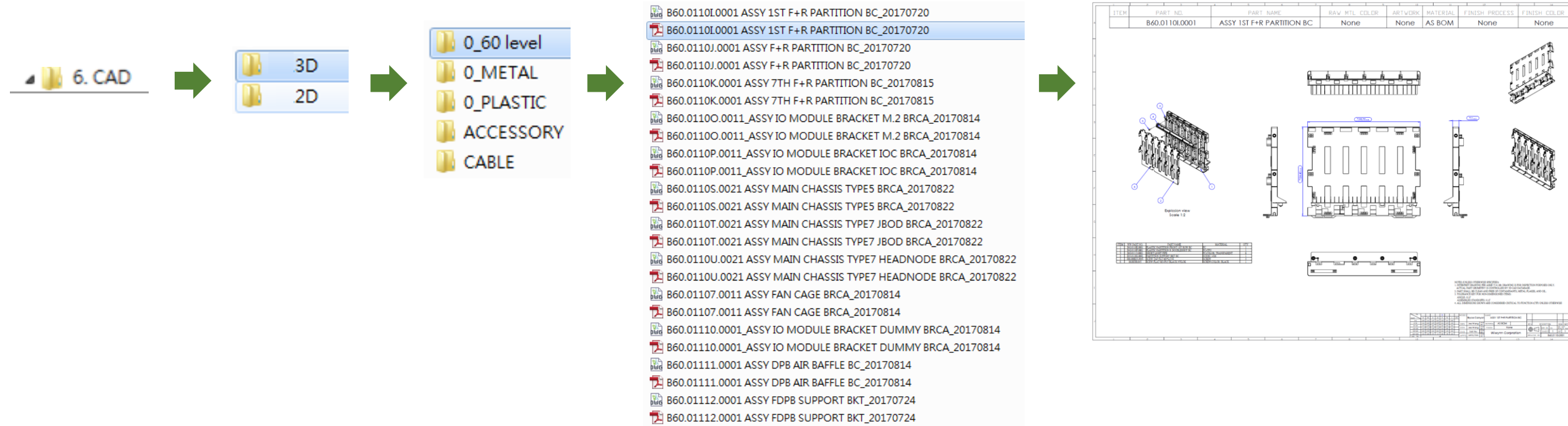


ME CAD(3D)





ME CAD(2D)

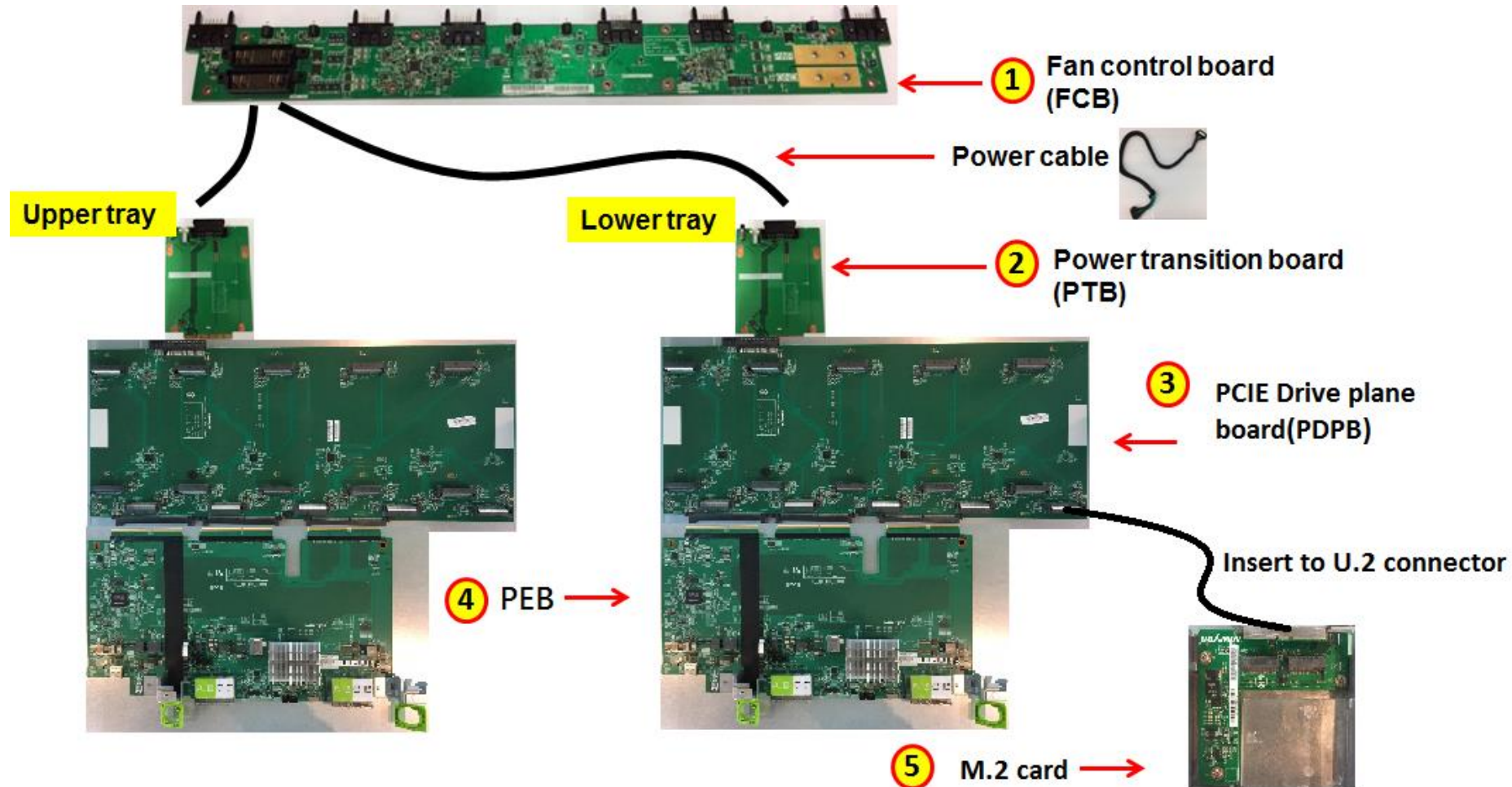


Lightning Contribution



Lightning System topology

Lightning has 5 types board, including FCB, PTB, PDPB, PEB and M.2 card.





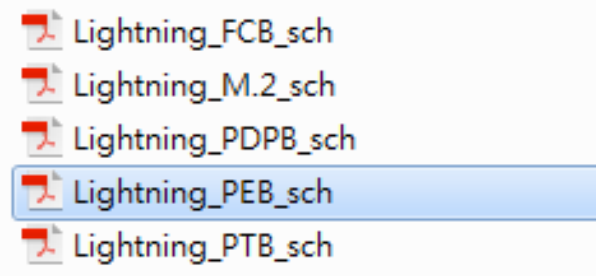
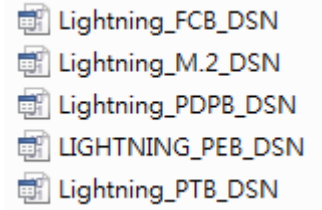
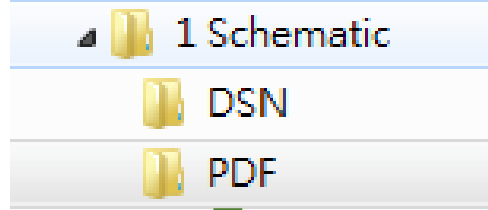
Design Files

The following folders are included in the zip file

- 1 Schematic:
Contain designed DSN files (Cadence OrCAD) and .pdf files
- 2 Layout and Stackup:
Contain designed BRD files (Allegro) and Excel files show detail stack up / Equal length table / SI constraints information
- 3 BOMs (Bill of material):
An excel file shows full component information. (Including EE & ME)
- 4 Manufacture files:
Gerber files for PCB manufacture and Excel files show component coordinates / Test coverage percentage.
- 5 Placement Map:
Contain component placement of top/bot view.
- 6 ME CAD(3D & 2D):
 - Contain all system Solidworks files and neutral file. (STEP)
 - Contain all chassis assemblies, metals, plastics, accessories, cables 2D files.
- oBMC:
 - <https://github.com/facebook/openbmc>



1 Schematic : DSN and PDF



Lightning - PMC PEB

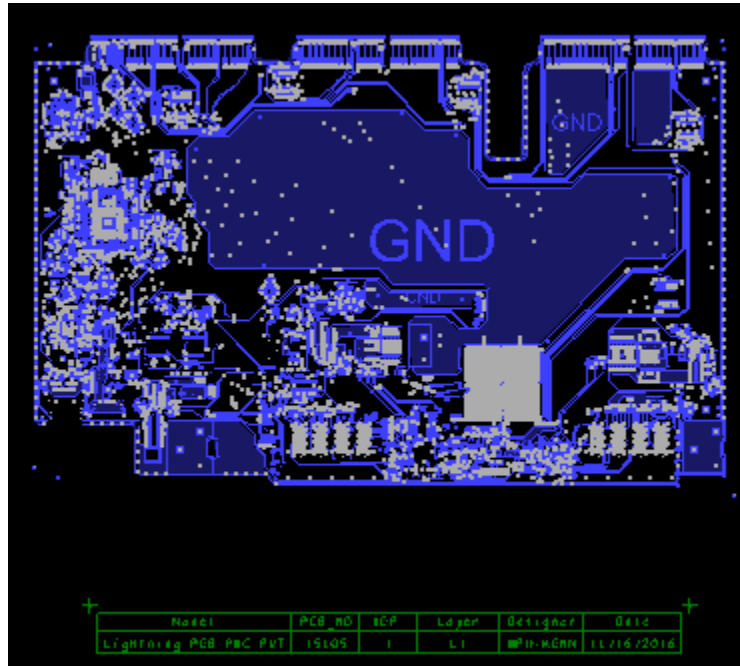
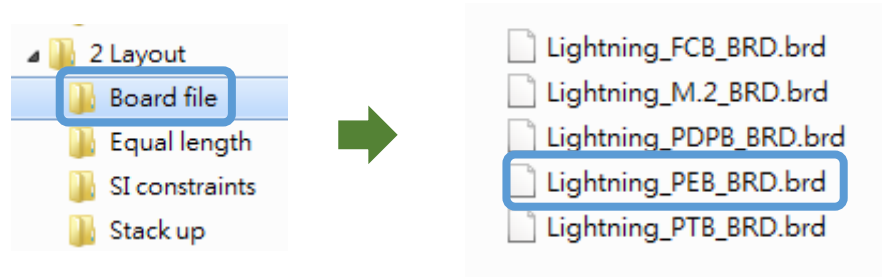
PCB P/N: 15105

Version: 1

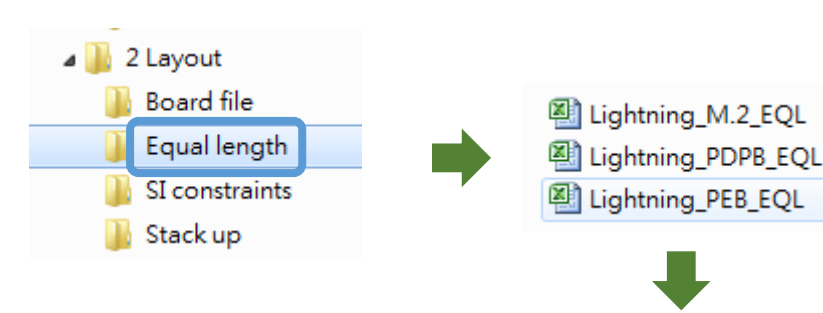
Project Code: BPD00Q010001

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15	AST2400 Power	55	History EVT1
16	AST2400 Strapping	56	History EVT2
17	AST2400_VOLTAGE SENSE	57	History DVT
18	BLANK	58	History DVT
19	LAN CONNECTOR	59	History DVT
20	USB2.0 x1	60	History PVT
21	I2C_BUFFER		
22	LED		

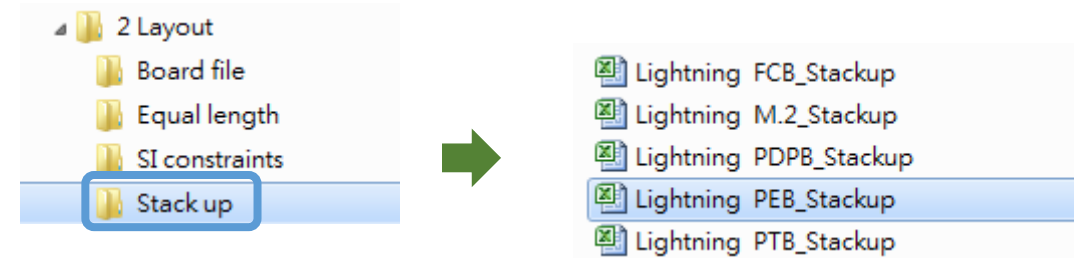
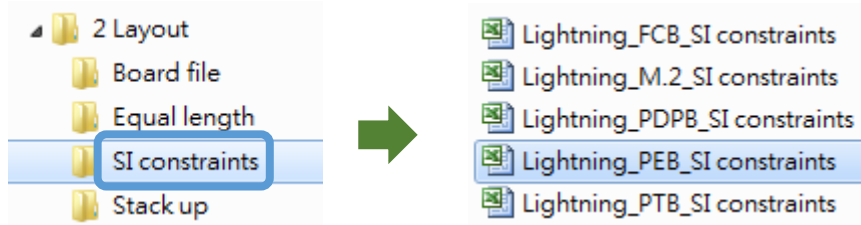


Model	PCB_NO	ICP	Layer	Designer	Date
Lightning PCB PMC PVT	15105	1	L1	MPH-KENN	11/16/2016

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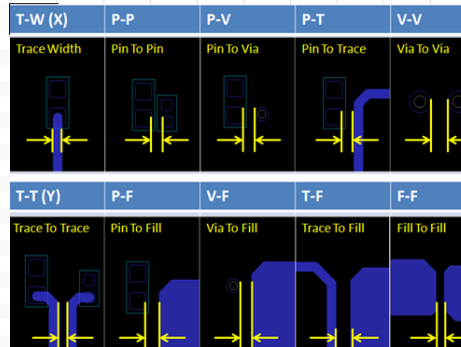


2 Layout : SI constraints and Stackup



Project Name: 15105-1
Project Path: C:\Users\10410614\Desktop\ICP\PEB\15105-1_20161102-1057.dtb

Net Name	Group Name	Type	Layer	T_W00	P-P	P-V	P-T	V-V	T_T(0)	P-F	V-F	T-F	T-T(2)	Ohm	Ref Layer
ADC_12V	ADC	BUS	1	4.75	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_12V	ADC	BUS	2	5	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_12V	ADC	BUS	3	5	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_12V	ADC	BUS	4	5	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_12V	ADC	BUS	5	5	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_12V	ADC	BUS	6	5	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_12V	ADC	BUS	7	5	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_12V	ADC	BUS	8	4.75	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_P0V9	ADC	BUS	1	4.75	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_P0V9	ADC	BUS	2	5	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_P0V9	ADC	BUS	3	5	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_P0V9	ADC	BUS	4	5	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_P0V9	ADC	BUS	5	5	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_P0V9	ADC	BUS	6	5	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_P0V9	ADC	BUS	7	5	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_P0V9	ADC	BUS	8	4.75	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_P0V9_E	ADC	BUS	1	4.75	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_P0V9_E	ADC	BUS	2	5	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_P0V9_E	ADC	BUS	3	5	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7
ADC_P0V9_E	ADC	BUS	4	5	5	5	5	5	5	5	5	5	5	50 Ohms	TOP+L2L3+L2/L4/L6+L5/L7/BOTTOM+L7



Board Number: 15105-1
Project Name: Lightning_PEB
Layer Count: 8 Layer
Date: 2016/10/19
Material: TUS80+CLP / N400T1+CLP
Order Part No.: 000000
Customer: Lohr-De
SI Engineer: S. Bringer
SI Engineer: S. Bringer

Version: 02

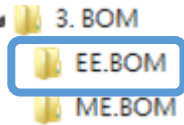
Layer	Cut out	Width	Thickness	Class/Copper Style	Woven	B	D1010	Imp Variation	Single Ended Types	Imp Variation	Differential Types
Top	Blank	0.8 sampling	0.5		3.4	0.0028			SS		100
Signal	0.8 sampling	2.1	0.5		3.4	0.0028			InnerCu=100%		InnerCu=100%
Prepreg	1.05	3	0.5		3.9	0.0028			PreCu=100%		PreCu=100%
Core	1.05	4	0.5		3.9	0.0028			PreCu=100%		PreCu=100%
Prepreg	1.05	18	0.5		4.2	0.0028			PreCu=100%		PreCu=100%
P-Cu/CLP	1.05	1.3	0.5		3.8	0.0028			PreCu=100%		PreCu=100%
P-Cu/CLP	1.05	4	0.5		3.8	0.0028			PreCu=100%		PreCu=100%
P-Cu/CLP	1.05	18	0.5		4.2	0.0028			PreCu=100%		PreCu=100%
P-Cu/CLP	1.05	1.3	0.5		3.9	0.0028			PreCu=100%		PreCu=100%
P-Cu/CLP	1.05	4	0.5		3.9	0.0028			PreCu=100%		PreCu=100%
P-Cu/CLP	1.05	18	0.5		4.2	0.0028			PreCu=100%		PreCu=100%
Bottom	Blank	0.8 sampling	0.5		3.4	0.0028			SS		100
Signal	0.8 sampling	2.1	0.5		3.4	0.0028			InnerCu=100%		InnerCu=100%
Prepreg	1.05	3	0.5		3.9	0.0028			PreCu=100%		PreCu=100%
Core	1.05	4	0.5		3.9	0.0028			PreCu=100%		PreCu=100%
Prepreg	1.05	18	0.5		4.2	0.0028			PreCu=100%		PreCu=100%
P-Cu/CLP	1.05	1.3	0.5		3.8	0.0028			PreCu=100%		PreCu=100%
P-Cu/CLP	1.05	4	0.5		3.8	0.0028			PreCu=100%		PreCu=100%
P-Cu/CLP	1.05	18	0.5		4.2	0.0028			PreCu=100%		PreCu=100%
P-Cu/CLP	1.05	1.3	0.5		3.9	0.0028			PreCu=100%		PreCu=100%
P-Cu/CLP	1.05	4	0.5		3.9	0.0028			PreCu=100%		PreCu=100%
P-Cu/CLP	1.05	18	0.5		4.2	0.0028			PreCu=100%		PreCu=100%

Note:

- Unit is mil
- The top thickness includes trace and solder mask
- Min hole copper thickness is 0.5 mil
- Min surface copper thickness is 1.5 mil
- Impedance Ck requirement +/- 3% (Report should be provided)
- PreCu=100% should design Center, Location and provide measurement results meeting following criteria:
 - 4.0000mil at 400Hz for stripline routing
 - 4.0000mil at 400Hz for microstrip routing

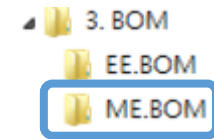


3 BOMs (EE & ME)



- Lightning_FCB_BOM
- Lightning_M.2_BOM
- Lightning_PDPB_BOM
- Lightning_PEB_BOM
- Lightning_PTB_BOM

Level	Parent Nur Part Numb	Description	Green Fact Life Cycle	Manufactu	Manufactu Source	BOM Usage	M/P Code	S/D	Qty	UoM	Location							
1	B55.00Q0	020.F0528 CONN CT.R2_SA,HF Released		FCI	91931-311 Single	Purchase	SMT		1	PCS	CN11							
1	B55.00Q0	062.10029 SKT SPI CR2_SA,HF Released		LOTES	ACA-SPI-C Single	Purchase	SMT		1	PCS	SKT4							
1	B55.00Q0	064.82R05 CHIP RES R2_SA,HF Released		ROHM,YA	MCR01M Multiple	Purchase	SMT		1	PCS	R958							
1	B55.00Q0	071.07311 IC EXPAN R2_SA,HF Released		MAXIM	MAX7311 Single	Purchase	SMT		5	PCS	U198 U199 U200 U201 U203							
1	B55.00Q0	071.08536 IC PCIE GR2_SA,HF Released		PMC	PM8536B-Single	Purchase	SMT		1	PCS	U1							
1	B55.00Q0	071.90431 IC CLK GR2_SA,HF Released		IDT	9FGV0431 Single	Purchase	SMT		1	PCS	U196							
1	B55.00Q0	072.02464 IC EEPROM R2_SA,HF Obsolete		MICROCE	24LC64-I Single	Purchase	SMT		1	PCS	U16							
1	B55.00Q0	072.42164 IC SDRAM R2_SA,HF Released		SAMSUNG	K4B2G16-Single	Purchase	SMT		1	PCS	U18							
1	B55.00Q0	074.01278 IC SWAP R2_SA,HF Released		ADI	ADM1278 Single	Purchase	SMT		1	PCS	U2							
1	B55.00Q0	074.06315 IC RESET R2_SA,HF Released		ANALOG	ADM6315 Single	Purchase	SMT		1	PCS	U82							
1	B55.00Q0	074.06654 IC TEMP R2_SA,HF Released		MAXIM	MAX6654 Single	Purchase	SMT		1	PCS	U4							
1	B55.00Q0	074.53355 IC PWM CR2_SA,HF Released		TI	TPS53355 Single	Purchase	SMT		2	PCS	PU1 PU3							
1	B55.00Q0	074.74801 IC LDO TI R2_SA,HF Released		TI	TPS74801 Single	Purchase	SMT		3	PCS	PU4 PU5 PU6							
1	B55.00Q0	077.51571 CHIP CAP R2_SA,HF Released		PANASON	EEJRX01 Single	Purchase	SMT		2	PCS	PTC38 TC17							
1	B55.00Q0	078.10421 CHIP CAP R2_SA,HF Released		MURATA	GRM033C Single	Purchase	SMT		169	PCS	C27 C28 C29 C30 C31 C32 C33 C34 C35 C36 C37 C38 C39 C40 C428 C42							
1	B55.00Q0	078.10711 CHIP CAP R2_SA,HF Released		MURATA	GRM21BC Multiple	Purchase	SMT		6	PCS	C454 C455 C456 C459 C494 C495							
1	B55.00Q0	078.22611 CHIP CAP R2_SA,HF Released		MURATA	GRM21BC Multiple	Purchase	SMT		2	PCS	PC66 PC68							
1	B55.00Q0	078.22622 CHIP CAP R2_SA,HF Released		MURATA	GRM31CC Single	Purchase	SMT		16	PCS	PC196 PC199 PC201 PC190 PC211 PC213 PC214 PC215 PC216 PC217 PC2							
1	B55.00Q0	078.47522 CHIP CAP R2_SA,HF Obsolete		DARFON	C2012X7F Multiple	Purchase	SMT		4	PCS	PC184 PC212 PC26 PC72							
1	B55.00Q0	082.30003 XTAL 32.R2_SA,HF Released		KDS	1TJF125D Single	Purchase	SMT		1	PCS	X2							
1	B55.00Q0	082.30005 XTAL 25N R2_SA,HF Released		HARMON	X3S02500 Single	Purchase	SMT		1	PCS	X3							

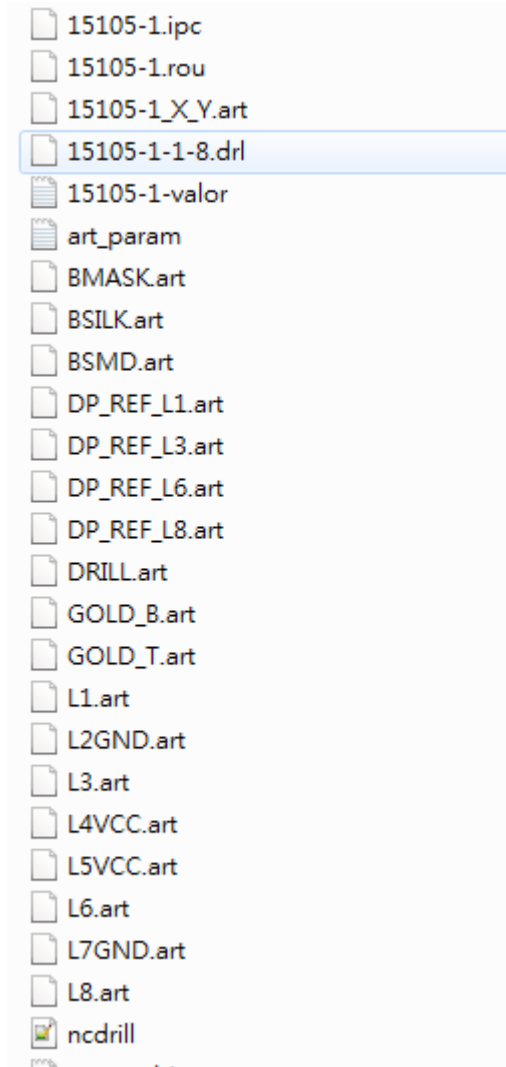
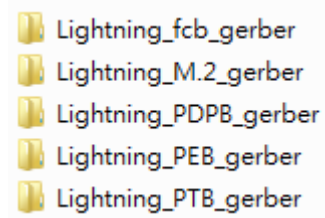
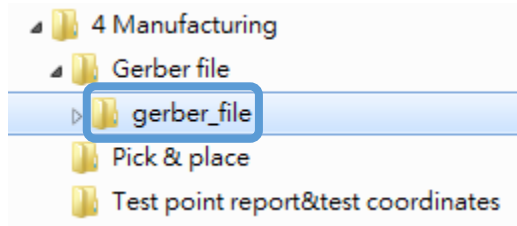


- Lightning Chassis BOM OCP
- Lightning M2 Carrier BOM
- Lightning U2 Carrier BOM

		Main housing	Old Part Number							
V	1	B60.00Q15.0001	B60.00Q0W.0001	ASSY MAIN HOUSING FOR LIGHTNING PVT		1	Priver			A
V	2	60.64W04.001		ASSY TOP COVER HU230		1	Priver			M
	3			CVR TOP COVER HU230		1	Priver	SGCC (T=1.0mm)		M
	3			28-411-201-5		2	Fiveteck	Hardened carbon steel	PENTON 376C	SC
	3			SO_04_L4		10	Priver			SO
	3			TOP_COVER_PIN		1	Priver			SO
V	2	60.64W05.001		ASSY LOWER CASE HU230		1	Priver			A
V	3	30.64W01.001		CAS LOWER CASE HU230		1	Priver	SGCC (T=1.6mm)		M
	4			SO-M3-L12.18MM-GUIDE		2	Priver			SO

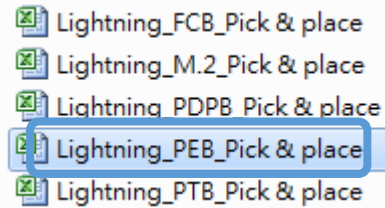
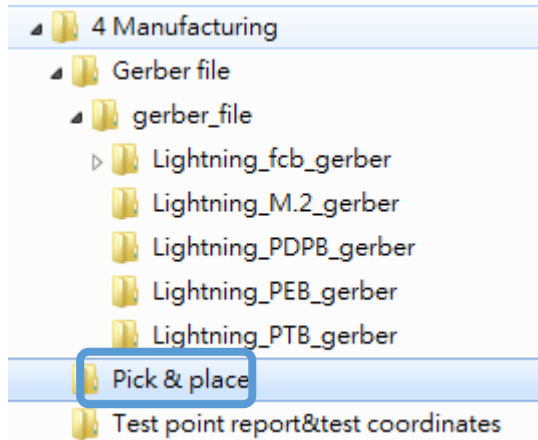


4 Manufacture Files : Gerber

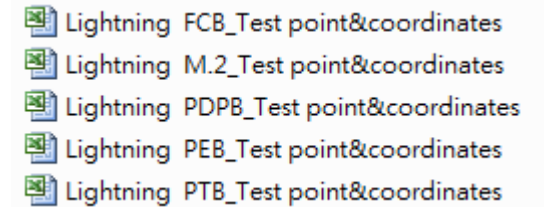
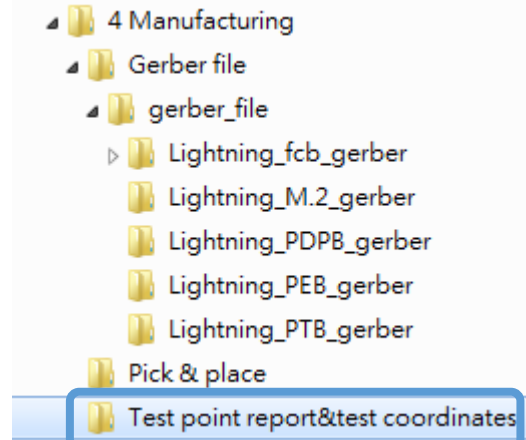




4 Manufacture Files : Pick & Place / Test point report



15105-1.1116WPH0457.brd								
Date Tue Mar 07 11:50:07 2017								
Total Components: 2560								
Component Report								
REFDES	COMP_DEVICE TYPE	COMP_VALUE	COMP_TOL	COMP_PACKAGE	SYM_X	SYM_Y	SYM_ROTATE	SYM_MIRROR
BAT1	AAA-BAT	AAA-BAT	0007.0091	AAA-BAT	4732.31	2552.45	270	NO
C1	C402H22	SCD22U1	78.22423.5	C402H22	10785	500	90	NO
C2	C402H22	SCD22U1	78.22423.5	C402H22	10785	535	90	NO
C4	C402H22	SCD1U16	78.10421.2	C402H22	8960	45	180	NO
C6	C402H22	SCD22U1	78.22423.5	C402H22	10785	605	90	NO
C7	C402H22	SCD22U1	78.22423.5	C402H22	10785	570	90	NO
C8	C402H22	SCD22U1	78.22423.5	C402H22	11279	1333	90	NO
C9	C402H22	SCD22U1	78.22423.5	C402H22	11279	1298	90	NO
C10	C402H22	SCD22U1	78.22423.5	C402H22	11385	1320	0	NO
C11	C402H22	SCD22U1	78.22423.5	C402H22	11420	1320	0	NO
C12	C402H22	SCD22U1	78.22423.5	C402H22	11579.07	1326.54	0	NO
C13	C402H22	SCD22U1	78.22423.5	C402H22	11614.07	1326.54	0	NO



PROJECT NAME:	15105-1
Total No. of Nets	1996
Testable Nets	1161
Untestable Nets	60
No. of Nets not required testpoint	775
Testability Percentage	58.17%
Total Testability Percentage	95.09%

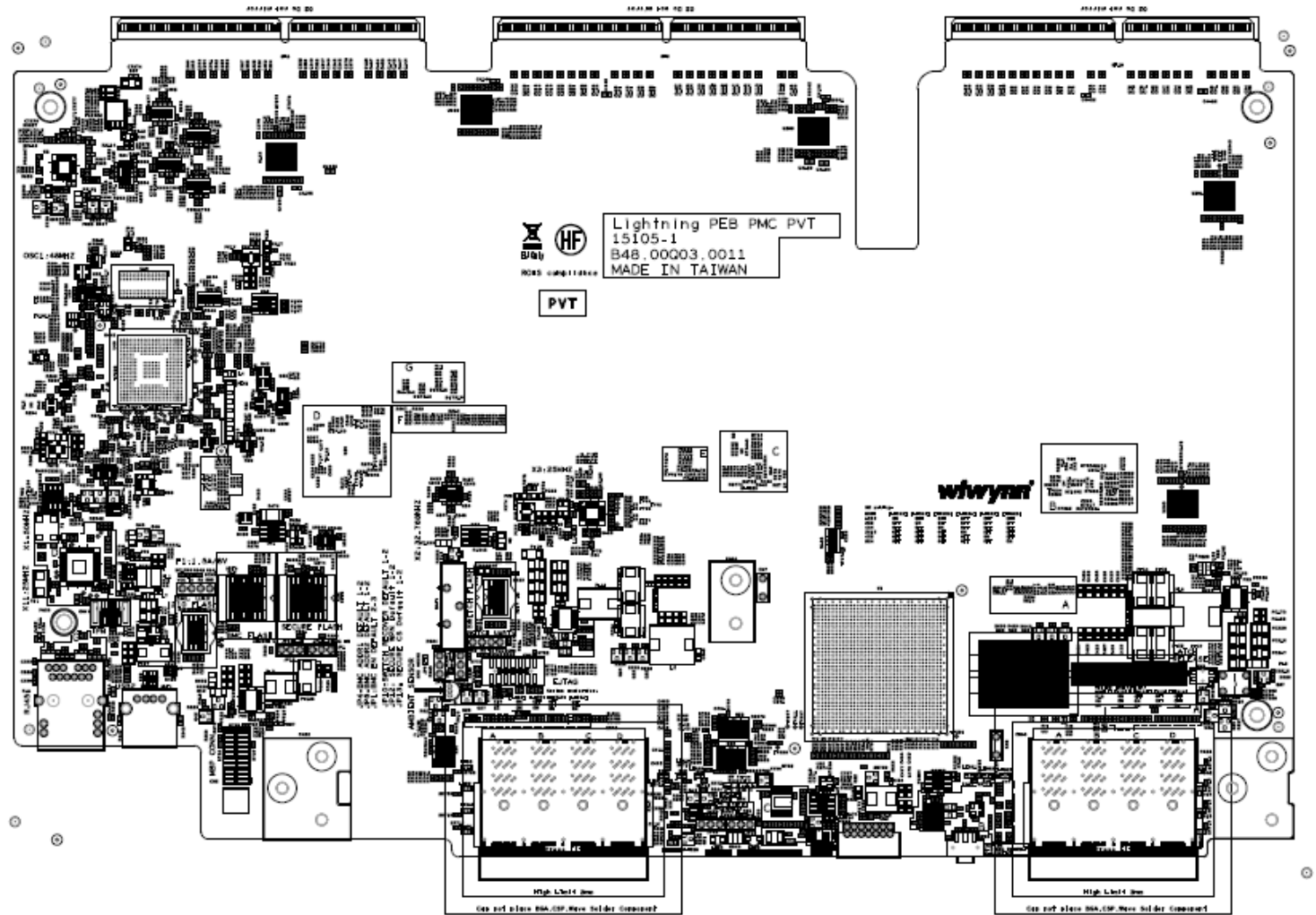
NETS NOT REQUIRED TO HAVE TESTPOINT				
CLK GEN AREA	Comment	NC PINS	Comment	HI-SPEED
50M_CLK_OUT		MB0_CM_SENSE_R1_P		8844_USB_DN1
50M_CLK_OUT_R		MB0_CM_SENSE_R1_N		8844_USB_DN2
CLK_N_2		MB0_CM_SENSE_P		8844_USB_DN3
CLK_N_4		MB0_CM_SENSE_N		8844_USB_DN4
CLK_N_6		ADM1278_HS_N		8844_USB_DN6
CLK_N_8		ADM1278_HS_P		8844_USB_DN7
CLK_P_2		P5V_STBY_FB		8844_USB_DN8
CLK_P_4		VR_P1V538_STBY_FB		8844_USB_DP1
CLK_P_6		VR_P1V28_STBY_FB		8844_USB_DP2
CLK_P_8		VR_P1V8_STBY_FB		8844_USB_DP3
CLKGEN_N1_R		P3V3_STBY_VBST		8844_USB_DP4
CLKGEN_N2_R		P3V3_STBY_VBST_RC		8844_USB_DP6
CLKGEN_N3_R		P3V3_STBY_LL		8844_USB_DP7



5 Placement Map

5 Placement Map

- Placement-FCB-Bot
- Placement-FCB-Top
- Placement-M.2-Bot
- Placement-M.2-Top
- Placement-PDPB-Bot
- Placement-PDPB-Top
- Placement-PEB-Bot
- Placement-PEB-Top
- Placement-PTB-Bot
- Placement-PTB-Top












6 ME CAD(2D & 3D files)

6. CAD



 1_Lightning SOLIDWORK PACK'GO	2017/1/9 下午 05...	檔案資料夾
 2_METAL 2D	2017/1/9 下午 05...	檔案資料夾
 3_METAL 3D STEP	2017/1/9 下午 05...	檔案資料夾
 4_PLASTIC 2D	2017/1/9 下午 05...	檔案資料夾
 5_PLASTIC 3D STEP	2017/1/9 下午 05...	檔案資料夾
 6_ASSEMBLY 2D	2017/1/9 下午 05...	檔案資料夾
 7_OUT PURCHASE 2D	2017/1/9 下午 05...	檔案資料夾

Thank you

